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**FINAL PRODUCT/PROCESS CHANGE NOTIFICATION**

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**Issue Date**

26-Jul-2006

**SUBJECT: ON Semiconductor Final Product/Process Change Notification #15611**

**TITLE: Final Notification - Qualification of the MAX809 MAX810 NCP803 on the AC MOS2 Technology**

**PROPOSED FIRST SHIP DATE: 26-Sep-2006**

**AFFECTED CHANGE CATEGORY(S): Die Shrink**

**AFFECTED PRODUCT DIVISION(S): Analog Power Management**

**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**

Contact your local ON Semiconductor Sales Office or Todd Manes <todd.manes@onsemi.com>

**SAMPLES:** Contact your local ON Semiconductor Sales Office

**ADDITIONAL RELIABILITY DATA:** Available

Contact your local ON Semiconductor Sales Office or Edmond Gallard <edmond.gallard@onsemi.com>

**NOTIFICATION TYPE:**

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 60 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

**DESCRIPTION AND PURPOSE:**

This is the final PCN to IPCN 15005 located at [www.onsemi.com](http://www.onsemi.com) announcing the completion of the qualification and redesign of the MAX80, MAX810, and NCP803 on the previous qualified AC MOS2 technology process at ON Semiconductor's MOS7A facility.

Die fabrication will continue at the current wafer fab site, ON Semiconductor MOS7A, in Aizu, Japan.

Assembly and final test will continue at the current qualified site (ON Semiconductor, Seremban, Malaysia).

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Device parameters will continue to meet all datasheet specifications and reliability will continue to meet or exceed ON Semiconductor standards.

**RELIABILITY DATA SUMMARY:**

Qualification testing included the following:

Test	Condition	Interval	SS	Results
HTOL	Ta=145C	168 hours	1x80	0/80
PC	MSL=1 3IR@260C	NA	1x160	0/160
TC+PC	-65/+150C	500 cycles	1x80	0/80
PC/UHAST	TA=130C RH=85% PSIG=18.8	96 hours	1x80	0/80
ED	-40/25/85/125C	NA	3 lots	PASS
ESD	HBM (2000V)	NA	2 lots	PASS
	MM (200V)	NA	2 lots	PASS
LU	ClassII/85C	NA	3 lots	PASS

**ELECTRICAL CHARACTERISTIC SUMMARY:**

Samples and characterization data are available upon request.

Datasheet specifications remain unchanged, with the exception that the guaranteed temperature range has been expanded to -40C to +125C.

**CHANGED PART IDENTIFICATION:**

Product with a date code after WW30 2006 may be sourced from either AC MOS1 or AC MOS2 die.

**AFFECTED DEVICE LIST****PART**

MAX809SN160T1  
 MAX809SN232T1  
 MAX809RTR  
 MAX809STR  
 MAX809TTR  
 MAX809JTR  
 MAX809MTR  
 MAX809HTR  
 MAX809LTR  
 MAX809SN490T1  
 MAX810RTR  
 MAX810STR  
 MAX810TTR  
 MAX810MTR



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**AFFECTED DEVICE LIST**

**PART**

MAX810LTR

NCP803SN160T1

NCP803SN232T1

NCP803SN263T1

NCP803SN293T1

NCP803SN308T1

NCP803SN438T1

NCP803SN463T1